CUI DEVICES

MODEL: HSB30-373710 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- low profile
- aluminum alloy

RoHS

MODEL

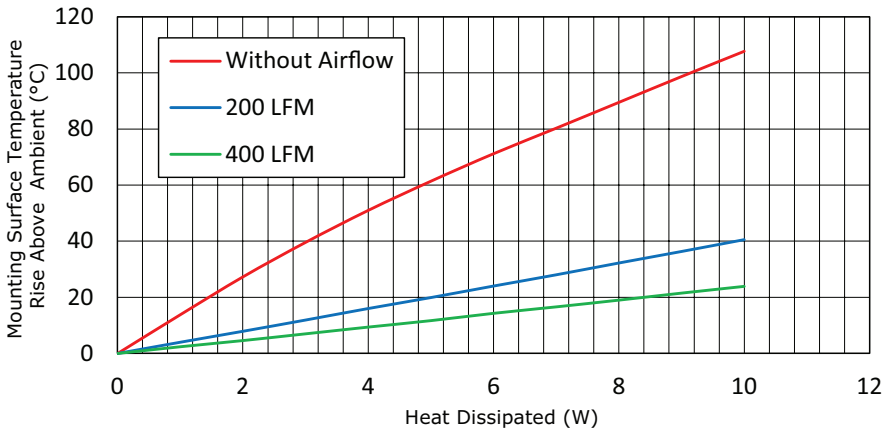
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSB30-373710	11.63	13.8	4.0	2.4	6.45

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	13.8	4.0	2.4
2	27.3	7.9	4.6
3	39.6	11.9	7.0
4	51.0	16.0	9.4
5	61.4	19.9	11.7
6	71.2	24.0	14.3
7	80.3	28.0	16.6
8	89.5	32.2	19.0
9	98.7	36.3	21.5
10	107.7	40.5	23.9

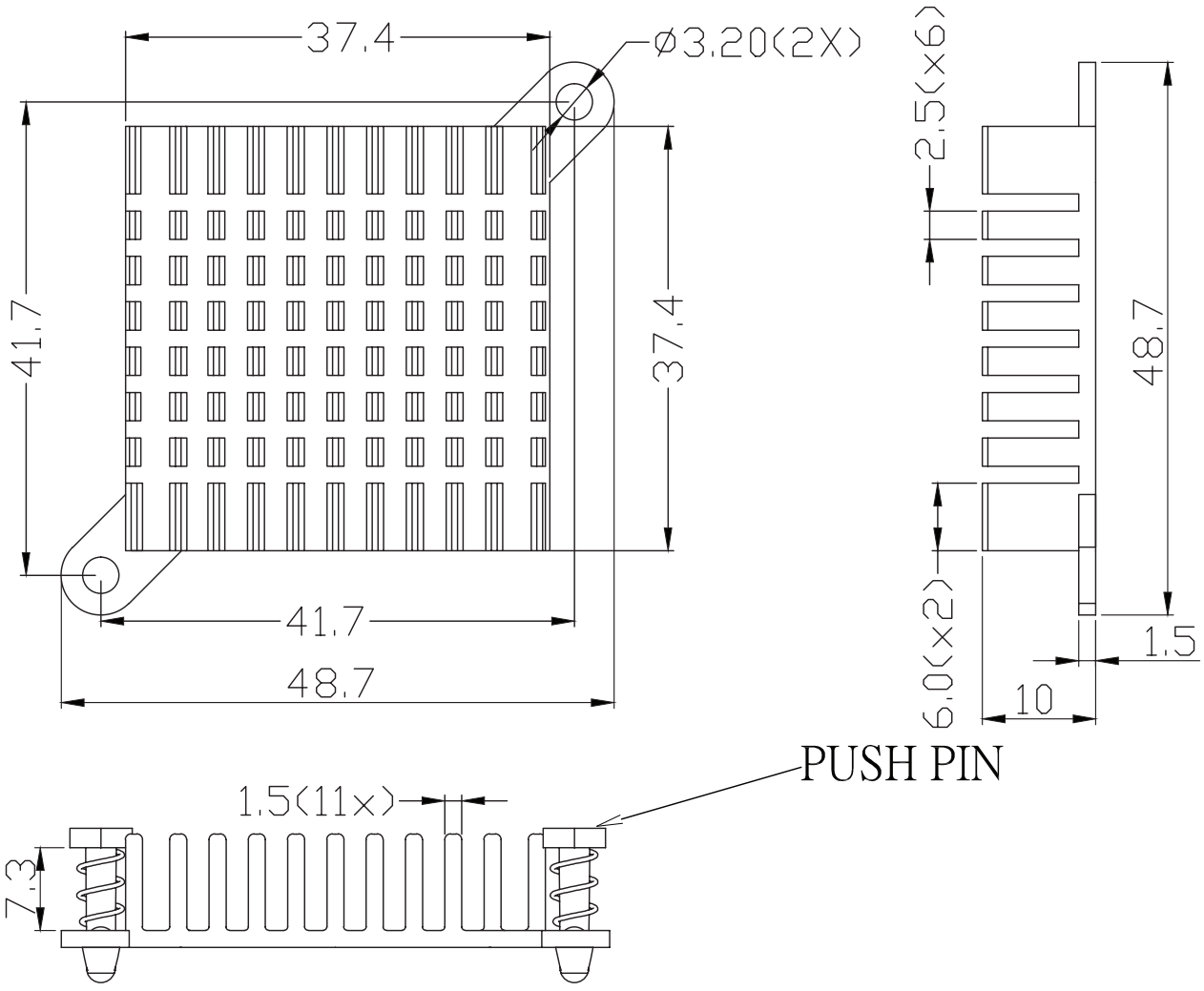
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	PA66
SPRING	spring steel, nickel plated
WEIGHT	20.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/22/2022

The revision history provided is for informational purposes only and is believed to be accurate.